

What is claimed is:

1. A hybrid integrated circuit device comprising:
  - a metal substrate provided with an insulating layer on a surface thereof;
  - a conductive pattern formed on a surface of the insulating layer;
  - a semiconductor element fixed onto the conductive pattern; and
  - a contact portion for electrically connecting the conductive pattern to the metal substrate in the vicinity of the semiconductor element.
2. The device of claim 1,
  - wherein the conductive pattern electrically connected to the metal substrate is connected to ground potential.
3. The device of claim 1,
  - wherein the surface of the metal substrate exposed by partially removing the insulating layer is electrically connected to the conductive pattern through a fine metal wire at the contact portion.
4. The device of claim 1,
  - wherein the conductive pattern and the semiconductor element constitute a D-class amplifier circuit.
5. The device of claim 1, further comprising:
  - a capacitor for short-circuiting a portion of the conductive pattern connected to the ground potential and a portion of the conductive pattern connected to a power source in the vicinity of the contact portion.
6. A hybrid integrated circuit device comprising:
  - a metal substrate provided with an insulating layer on a surface thereof;
  - a conductive pattern formed on a surface of the insulating layer;
  - a semiconductor element being fixed onto the conductive pattern and constituting a bridge circuit; and
  - a contact portion for electrically connecting the metal substrate in the vicinity of the semiconductor element to the conductive pattern connected to ground potential.
7. The device of claim 6,

wherein the surface of the metal substrate exposed by partially removing the insulating layer is electrically connected to the conductive pattern through a fine metal wire at the contact portion.

8. The device of claim 6, further comprising:

a capacitor for short-circuiting a portion of the conductive pattern connected to the ground potential and a portion of the conductive pattern connected to a power source in the vicinity of the contact portion.

9. The device of claim 6,

wherein the a plurality of bridge circuits are provided, and  
the contact portion is provided to each of the bridge circuits.